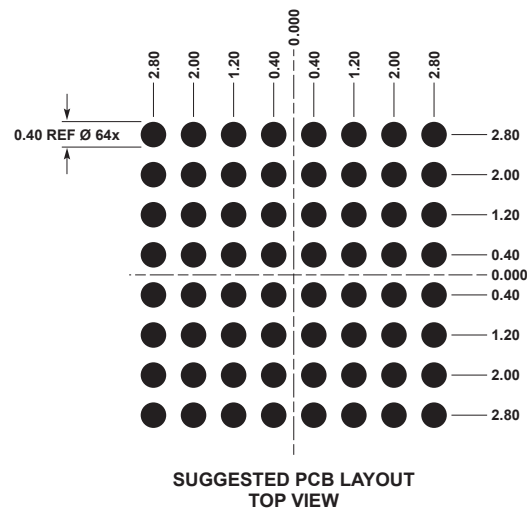
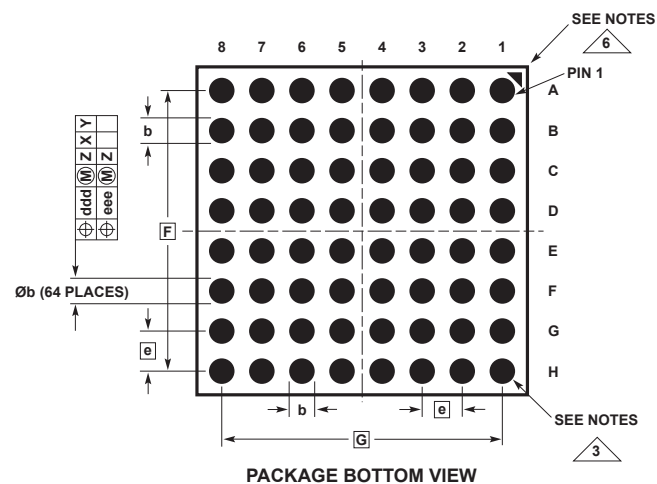
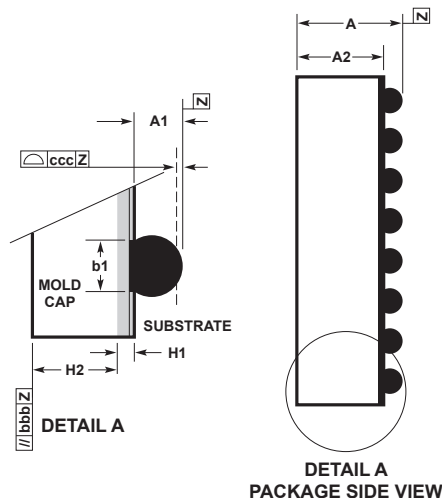
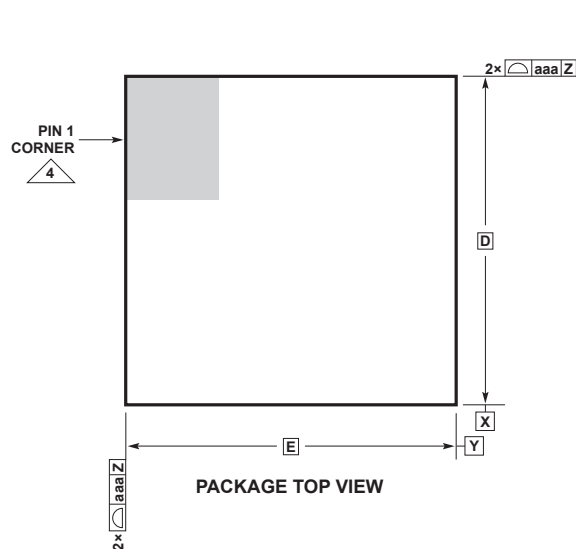


64-Ball Chip Scale Package Ball Grid Array [CSP_BGA]
(7.00mm × 7.00mm × 1.85mm)
(Reference DWG # BC-64-9)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	1.70	1.85	2.00	
A1	0.30	0.40	0.50	BALL HT
A2	1.36	1.45	1.54	
b	0.45	0.50	0.55	BALL DIMENSION
b1	0.37	0.40	0.43	PAD DIMENSION
D		7.00		
E		7.00		
e		0.80		
F		5.60		
G		5.60		
H1		0.25 REF		SUBSTRATE THK
H2		1.20 REF		MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.15	
eee			0.08	

TOTAL NUMBER OF BALLS: 64

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

2. ALL DIMENSIONS ARE IN MILLIMETERS

3 BALL DESIGNATION PER JEP95

4 DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN 1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6  PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

